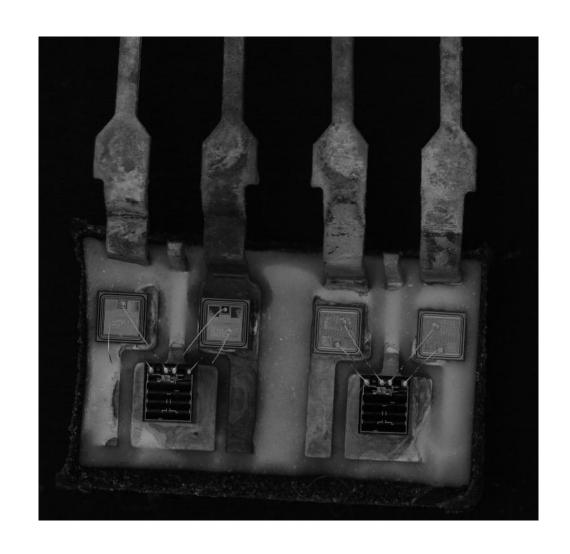
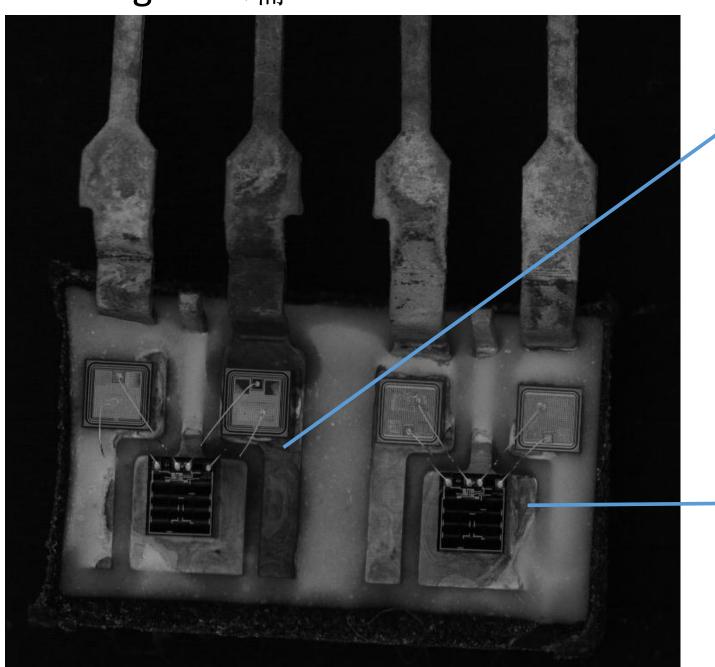
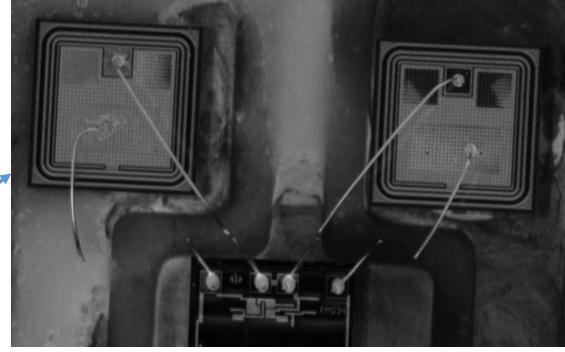
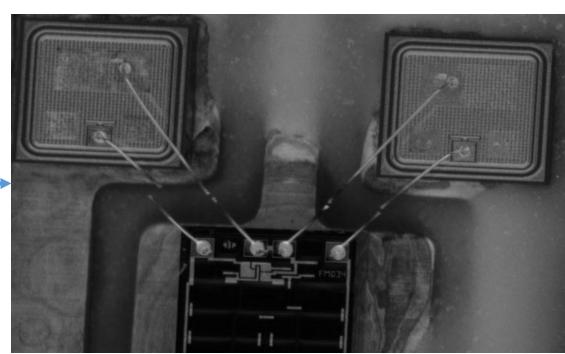
Wirebonding 3D Inspection



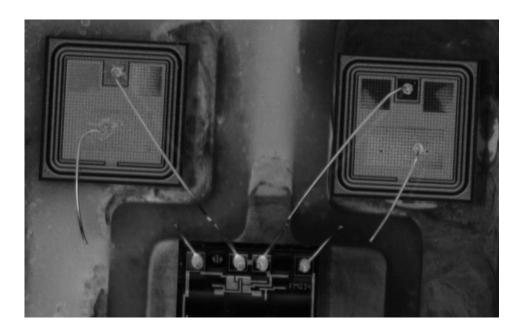
2D Image: PD端

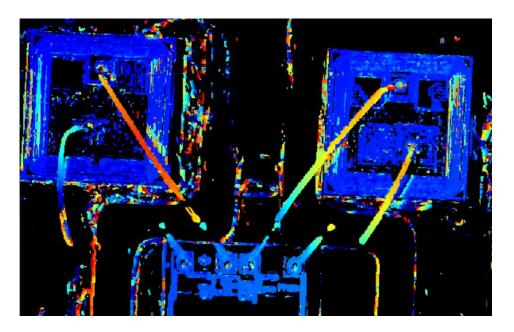


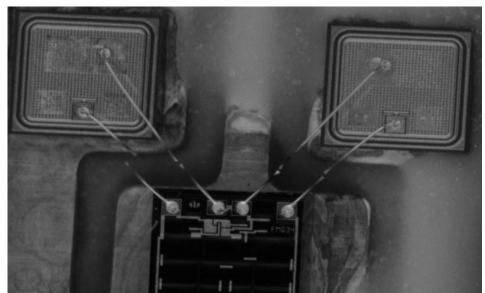


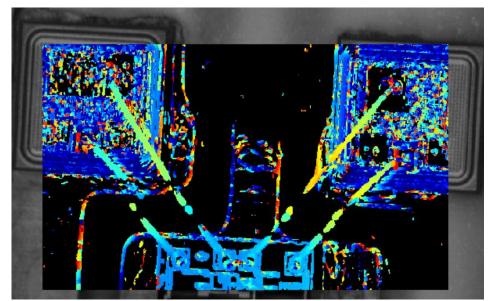


3D Image: PD端

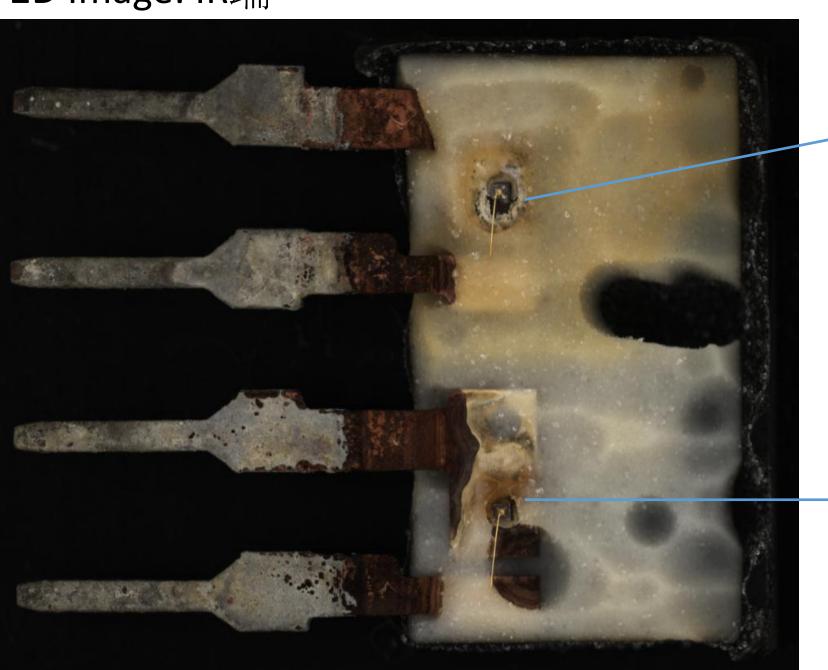








2D Image: IR端







3D Image: IR端

```
< 0.348 [mm]
```

< 0.307 [mm]

< 0.266 [mm]

< 0.225 [mm]

< 0.184 [mm]

< 0.143 [mm]

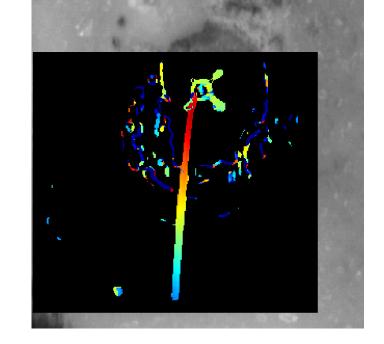
< 0.102 [mm]

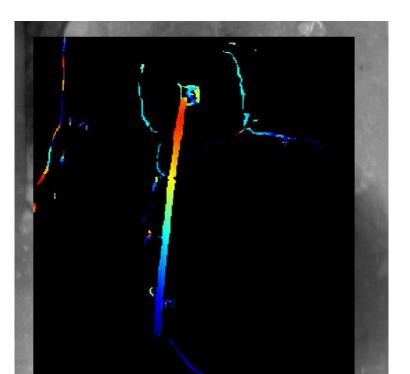
< 0.061 [mm]

< 0.020 [mm]









3D Inspection Process Point

以影像處理方式將Wire與背景分離,取出的Wire進行3D計算將可得到更佳之計算結果



